

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	51410	image near sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT
2	BRS	L2	493	1 and packaging	USPAT; US-PGPUB; EPO; JPO; DERWENT
3	BRS	L3	1774	1 and (package packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT
4	BRS	L4	925	3 and (chip die (semiconductor near1 device))	USPAT; US-PGPUB; EPO; JPO; DERWENT
5	BRS	L5	117	4 and (image near1 sens\$3 near1 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT
6	BRS	L6	802	image near1 sens\$3 near1 chip	USPAT; US-PGPUB; EPO; JPO; DERWENT
7	BRS	L7	51	5 and transparent	USPAT; US-PGPUB; EPO; JPO; DERWENT
8	BRS	L8	200	6 and transparent	USPAT; US-PGPUB; EPO; JPO; DERWENT
9	BRS	L9	155	8 and (base substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT
10	BRS	L10	42	9 and (plastic epoxy bt fr4 fr5 ppe)	USPAT; US-PGPUB; EPO; JPO; DERWENT
11	BRS	L18	113	9 not 10	USPAT; US-PGPUB; EPO; JPO; DERWENT
12	BRS	L19	99	image near1 sens\$3 near1 package	USPAT; US-PGPUB; EPO; JPO; DERWENT
13	BRS	L20	42	19 and transparent	USPAT; US-PGPUB; EPO; JPO; DERWENT
14	BRS	L21	39	20 not 10	USPAT; US-PGPUB; EPO; JPO; DERWENT
15	BRS	L22	22	21 and (substrate base)	USPAT; US-PGPUB; EPO; JPO; DERWENT
16	BRS	L30	418	(image optical) near1 sens\$3 near3 (package packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT
17	BRS	L31	57	19 not 20	USPAT; US-PGPUB; EPO; JPO; DERWENT
18	BRS	L32	19	31 and (substrate base)	USPAT; US-PGPUB; EPO; JPO; DERWENT
19	BRS	L33	38	31 not 32	USPAT; US-PGPUB; EPO; JPO; DERWENT
20	BRS	L34	102	30 and (wire wiring) and (substrate base pcb (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT
21	BRS	L35	75	34 not 19	USPAT; US-PGPUB; EPO; JPO; DERWENT
22	BRS	L42	1930	257/774	USPAT; US-PGPUB; EPO; JPO; DERWENT
23	BRS	L43	23	42 and ((image optical) near1 sens\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT

	Time Stamp	Comments	Error Definition	Errors
1	2002/01/26 12:56			0
2	2002/01/26 12:51			0
3	2002/01/26 12:52			0
4	2002/01/26 14:37			0
5	2002/01/26 12:54			0
6	2002/01/26 13:19			0
7	2002/01/26 12:57			0
8	2002/01/26 13:20			0
9	2002/01/26 12:58			0
10	2002/01/26 13:00			0
11	2002/01/26 13:18			0
12	2002/01/26 13:38			0
13	2002/01/26 13:20			0
14	2002/01/26 13:20			0
15	2002/01/26 13:20			0
16	2002/01/26 14:15			0
17	2002/01/26 13:41			0
18	2002/01/26 13:42			0
19	2002/01/26 13:43			0
20	2002/01/26 13:47			0
21	2002/01/26 13:47			0
22	2002/01/26 14:25			0
23	2002/01/26 14:16			0

	Type	L #	Hits	Search Text	DBs
24	BRS	L44	36	42 and ((image optical) near1 (device sens\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT
25	BRS	L45	868	257/433	USPAT; US-PGPUB; EPO; JPO; DERWENT
26	BRS	L49	267	45 and (chip die (semiconductor near1 device)) and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT
27	BRS	L50	261	49 not 5	USPAT; US-PGPUB; EPO; JPO; DERWENT
28	BRS	L51	258	50 not 8	USPAT; US-PGPUB; EPO; JPO; DERWENT
29	BRS	L52	250	51 not 34	USPAT; US-PGPUB; EPO; JPO; DERWENT
30	BRS	L53	249	52 not 44	USPAT; US-PGPUB; EPO; JPO; DERWENT
31	BRS	L54	249	53 not 18	USPAT; US-PGPUB; EPO; JPO; DERWENT
32	BRS	L55	249	54 not 19	USPAT; US-PGPUB; EPO; JPO; DERWENT
33	BRS	L56	167	55 and (transparent glass)	USPAT; US-PGPUB; EPO; JPO; DERWENT
34	BRS	L60	1	"6262479"	USPAT; US-PGPUB; EPO; JPO; DERWENT
35	BRS	L61	7	1 and ((contact conductive electrode) with tape with tear\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT
36	BRS	L62	3	"6215179"	USPAT; US-PGPUB; EPO; JPO; DERWENT
37	BRS	L63	1	"6247229"	USPAT; US-PGPUB; EPO; JPO; DERWENT
38	BRS	L64	14	"5866939"	USPAT; US-PGPUB; EPO; JPO; DERWENT
39	BRS	L65	5	"6054772"	USPAT; US-PGPUB; EPO; JPO; DERWENT
40	BRS	L66	20	63 64 65	USPAT; US-PGPUB; EPO; JPO; DERWENT

	Time Stamp	Comments	Error Definition	Errors
24	2002/01/26 14:17			0
25	2002/01/26 14:25			0
26	2002/01/26 14:38			0
27	2002/01/26 14:39			0
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29	2002/01/26 14:40			0
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31	2002/01/26 14:41			0
32	2002/01/26 14:41			0
33	2002/01/26 14:55			0
34	2002/01/26 14:55			0
35	2002/01/26 17:21			0
36	2002/01/26 17:22			0
37	2002/01/26 17:24			0
38	2002/01/26 17:28			0
39	2002/01/26 17:33			0
40	2002/01/26 17:33			0